

General Description

The UI(D)4N60 is the highest performance trench P-ch MOSFETs with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The UI(D)4N60 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

Absolute Maximum Ratings

Symbol	Parameter	TO-251/TO-252	Unites
V_{DSS}	Drain-Source Voltage	600	V
I_D	Drain Current –Continuous($T_C = 25^\circ\text{C}$) –Continuous($T_C = 100^\circ\text{C}$)	3.2	A
		1.9	A
I_{DM}	Drain Current –Pulsed (Note1)	12.8	A
V_{GSS}	Gate-Source Voltage	± 30	V
E_{AS}	Single Pulsed Avalanche Energy (Note2)	63	mJ
dv/dt	Peak Diode Recovery dv/dt (Note3)	4.5	V/ns
P_D	Power Dissipation ($T_C = 25^\circ\text{C}$) -Derate above 25°C	57	W
		0.45	W/ $^\circ\text{C}$
$T_{J1} T_{STG}$	Operating and Storage Temperature Range	-55 to + 150	$^\circ\text{C}$
T_L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300	$^\circ\text{C}$

Thermal Data

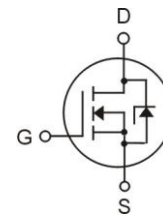
Symbol	Parameter	Typ	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	--	2.2	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	--	50	$^\circ\text{C/W}$

Product Summary

BV_{DSS}	$R_{DS(ON)}$	I_D
600V	2.25 Ω	3.2A

Applications

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

TO-251/TO-252 Pin Configuration


Electrical Characteristics ($T_J=25\text{ }^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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Off Characteristics

BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 250\mu\text{A}$	600	--	--	V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = 250\mu\text{A}$, Referenced to 25°C	--	0.6	--	$V/^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 600\text{ V}, V_{GS} = 0\text{ V}$ ($T_C = 25^\circ\text{C}$)	--	--	10	μA
		$V_{DS} = 480\text{ V}, V_{GS} = 0\text{ V}$ ($T_C = 125^\circ\text{C}$)	--	--	100	μA
I_{GSSF}	Gate-Body Leakage Current, Forward	$V_{GS} = 30\text{ V}, V_{DS} = 0\text{ V}$	--	--	100	nA
I_{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -30\text{ V}, V_{DS} = 0\text{ V}$	--	--	-100	nA

On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	2.5	3.5	4.5	V
$R_{DS(on)}$	Static Drain-Source On-resistance	$V_{GS} = 10\text{ V}, I_D = 1.6\text{A}$	--	2.25	2.81	Ω
g_{FS}	Forward Transconductance	$V_{DS} = 10\text{ V}, I_D = 1.6\text{A}$ (Note 4)	--	2.6	--	S

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = 25\text{ V}, V_{GS} = 0\text{ V},$ $f = 1.0\text{ MHz}$	--	500	650	pF
C_{oss}	Output Capacitance		--	53.2	69	pF
C_{riss}	Reverse Transfer Capacitance		--	7.0	9.1	pF

Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 300\text{ V}, I_D = 3.2\text{A},$ $R_G = 25\Omega$ (Note 4, 5)	--	11	27	ns
t_r	Turn-On Rise Time		--	20	48	ns
$t_{d(off)}$	Turn-Off Delay Time		--	30	72	ns
t_f	Turn-Off Fall Time		--	19	46	ns
Q_g	Total Gate Charge	$V_{DS} = 480\text{ V}, I_D = 3.2\text{A},$ $V_{GS} = 10\text{ V}$ (Note 4, 5)	--	14.5	20	nC
Q_{gs}	Gate-Source Charge		--	3.4	--	nC
Q_{gd}	Gate-Drain Charge		--	7.0	--	nC

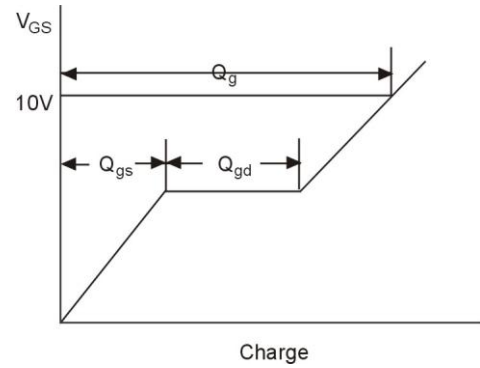
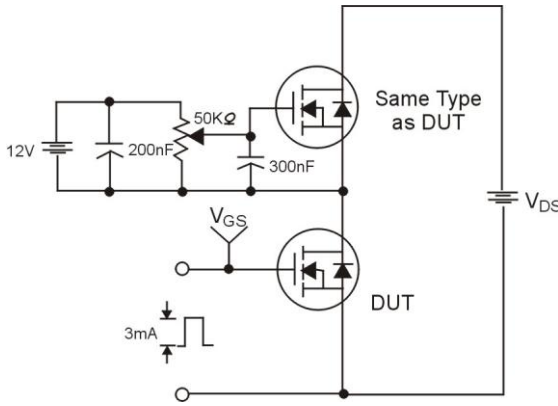
Drain-Source Diode Characteristics and Maximum Ratings

I_S	Maximum Continuous Drain-Source Diode Forward Current	--	--	3.2	A	
I_{SM}	Maximum Pulsed Drain-Source Diode Forward Current	--	--	12.8	A	
V_{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0\text{ V}, I_S = 3.2\text{A}$	--	1.13	1.4	V
t_{rr}	Reverse Recovery Time	$V_{GS} = 0\text{ V}, I_S = 3.2\text{A},$ $di_f/dt = 100\text{ A}/\mu\text{s}$ (Note 4)	--	561	--	ns
Q_{rr}	Reverse Recovery Charge		--	0.8	--	μC

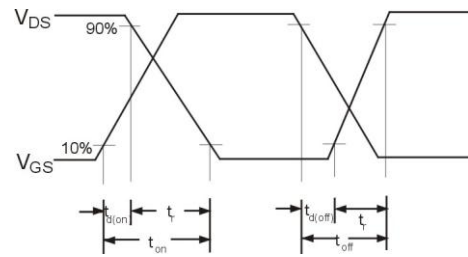
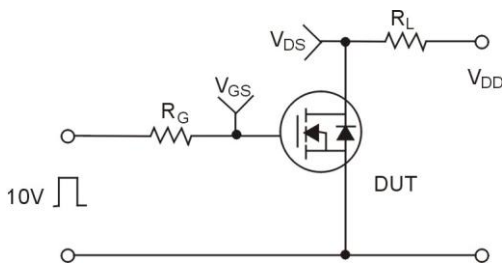
Notes:

1. Repetitive Rating : Pulse width limited by maximum junction temperature
2. $L = 10\text{mH}, I_{AS} = 3.4\text{A}, V_{DD} = 50\text{V}, R_G = 25\Omega$, Starting $T_J = 25^\circ\text{C}$
3. $I_{SD} \leq 3.2\text{A}, di/dt \leq 200\text{A}/\mu\text{s}, V_{DD} \leq BV_{DSS}$, Starting $T_J = 25^\circ\text{C}$
4. Pulse Test : Pulse width $\leq 300\mu\text{s}$, Duty cycle $\leq 2\%$
5. Essentially independent of operating temperature

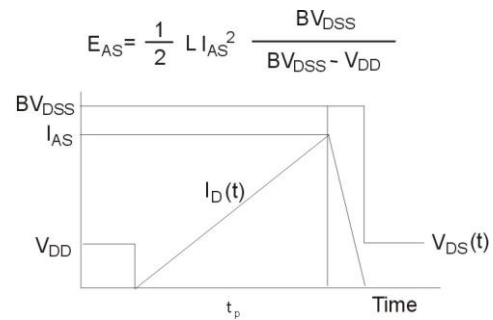
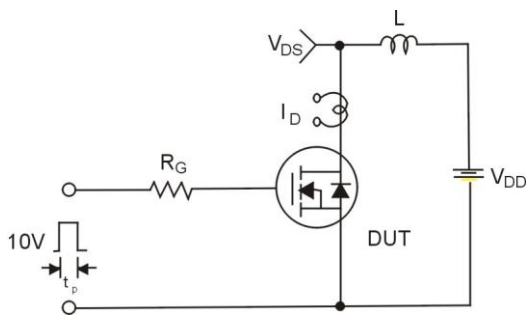
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms



Peak Diode Recovery dv/dt Test Circuit & Waveforms
